



60V P-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)} max	I _D max T _A = +25°C	
001/	110mΩ @ V _{GS} = -10V	-4.5A	
-60V	130mΩ @ V _{GS} = -4.5V	-4.2A	

Description and Applications

This MOSFET has been designed to minimize the on-state resistance ($R_{DS(ON)}$) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

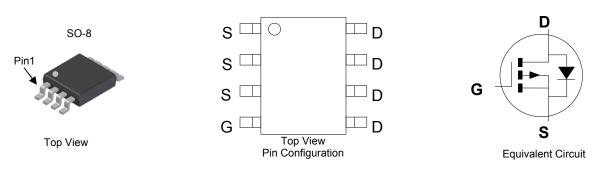
- Backlighting
- Power Management Functions
- DC-DC Converters

Features and Benefits

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/ Output Leakage
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208 3
- Weight: 0.072g (approximate)



Ordering Information (Note 4)

Part Number	Case	Packaging
DMP6110SSS-13	SO-8	2500/Tape & Reel

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

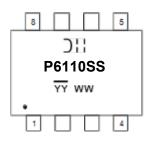
2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

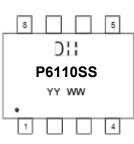
4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information

Notes:



Chengdu A/T Site



);; = Manufacturer's Marking
P6110SS = Product Type Marking Code
YYWW = Date Code Marking
YY or YY = Year (ex: 14 = 2014)
WW = Week (01 - 53)
YY = Date Code Marking for SAT (Shanghai Assembly/ Test site)
YY = Date Code Marking for CAT (Chengdu Assembly/ Test site)

Shanghai A/T Site



NEW PRODUCT

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	V _{DSS}	-60	V	
Gate-Source Voltage		V _{GSS}	±20	V
Drain Current (Note 6) V _{GS} = -10V t < 10s	T _A = +25°C T _A = +70°C	ID	-4.5 -3.6	A
Maximum Body Diode Forward Current (Note 6)		ls	-2.1	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)	I _{DM}	-19	А	
Avalanche Current (Notes 7) L = 0.1mH	I _{AS}	-17.6	А	
Avalanche Energy (Notes 7) L = 0.1mH	E _{AS}	15.4	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)		PD	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	D	80	°C/W
memai Resistance, Junction to Ambient (Note 5)	t<10s	R _{θJA}	48	°C/W
Total Power Dissipation (Note 6)		PD	2.0	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	D	61	°C/W
	t<10s	R _{θJA}	37	°C/W
Thermal Resistance, Junction to Case		R _{θJC}	6.4	°C/W
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)	• • • • • •		. 76		•		
Drain-Source Breakdown Voltage	BV _{DSS}	-60	_		V	V _{GS} = 0V, I _D = -250µA	
Zero Gate Voltage Drain Current	I _{DSS}		—	-1	μA	$V_{DS} = -48V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	100	nA	$V_{GS} = \pm 16V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)	•		•		•	÷	
Gate Threshold Voltage	V _{GS(th)}	-1	—	-3	V	$V_{DS} = V_{GS}, I_D = -250 \mu A$	
Static Drain-Source On-Resistance	P	_	86	110	mΩ	V _{GS} = -10V, I _D = -4.5A	
Static Drain-Source On-Resistance	R _{DS (ON)}	_	98	130	11122	V _{GS} = -4.5V, I _D =-3.5A	
Diode Forward Voltage	V _{SD}	_	-0.7	-1.2	V	V _{GS} = 0V, I _S = -1A	
DYNAMIC CHARACTERISTICS (Note 9)			_		_		
Input Capacitance	C _{iss}	_	1030	_	pF	V _{DS} = -30V, V _{GS} = 0V, f = 1.0MHz	
Output Capacitance	C _{oss}	_	49.1	_			
Reverse Transfer Capacitance	C _{rss}	_	38.7				
Gate Resistance	R _G	_	13.6	_	Ω	V _{DS} = 0V, V _{GS} = 0V, f = 1.0MHz	
Total Gate Charge (V _{GS} = -4.5V)	Qg		9.5				
Total Gate Charge (V _{GS} = -10V)	Qg		19.4		nC	V _{DS} = -30V, I _D = -5A	
Gate-Source Charge	Q _{gs}		2.3		nc		
Gate-Drain Charge	Q _{gd}	_	3.6	_			
Turn-On Delay Time	t _{D(on)}		3.7				
Turn-On Rise Time	tr		6.3		ns	$\label{eq:VGS} \begin{array}{l} V_{\mathrm{GS}} \texttt{=} \texttt{-10V}, V_{\mathrm{DS}} \texttt{=} \texttt{-30V}, R_{\mathrm{GEN}} \texttt{=} \texttt{6}\Omega, \\ I_{\mathrm{D}} \texttt{=} \texttt{-5A} \end{array}$	
Turn-Off Delay Time	t _{D(off)}		58.7				
Turn-Off Fall Time	tf		26.1		1		
Body Diode Reverse Recovery Time	t _{rr}	_	14.85	_	ns	I _S = -5A, dI/dt = 100A/µs	
Body Diode Reverse Recovery Charge	Q _{rr}	_	8.8	_	nC	I _S = -5A, dI/dt = 100A/µs	

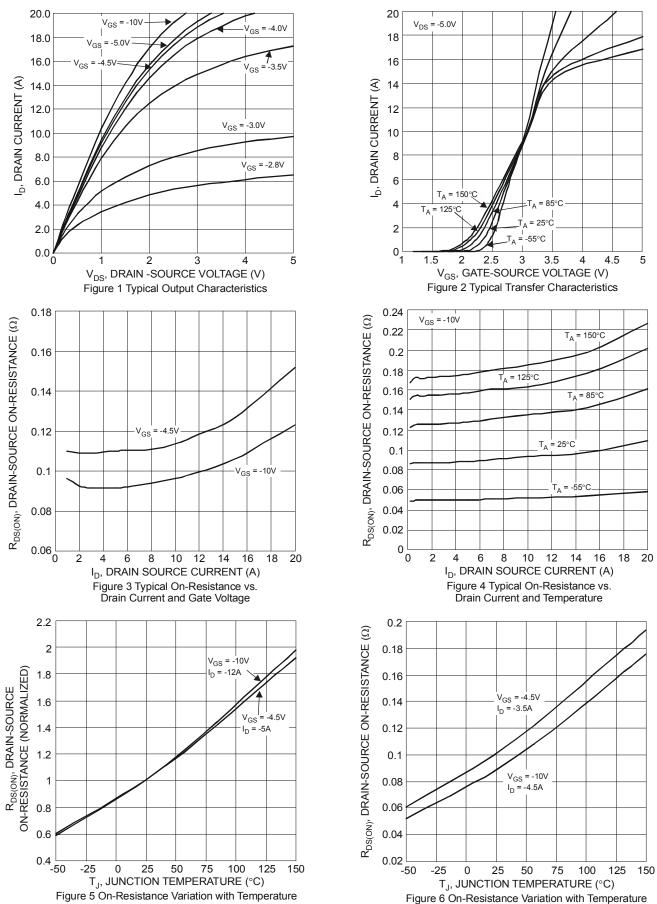
 Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
 Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate. Notes:

7. UIS in production with L = 0.1mH, starting $T_A = +25^{\circ}C$.

8. Short duration pulse test used to minimize self-heating effect.
 9. Guaranteed by design. Not subject to product testing.

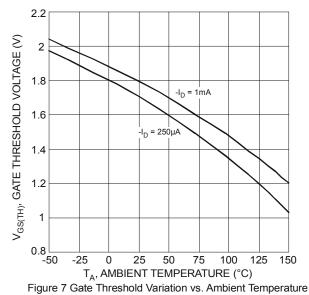


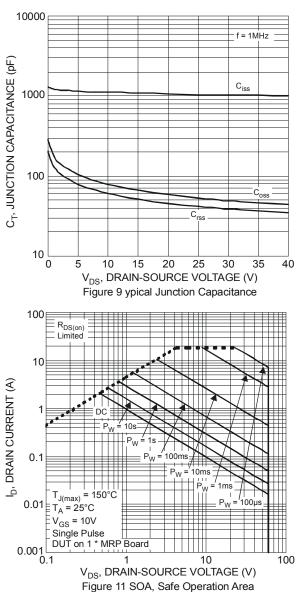
DMP6110SSS

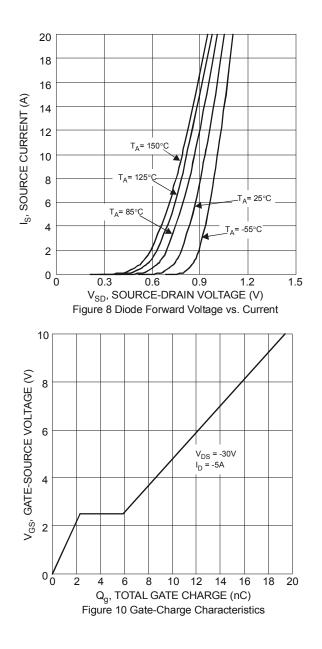


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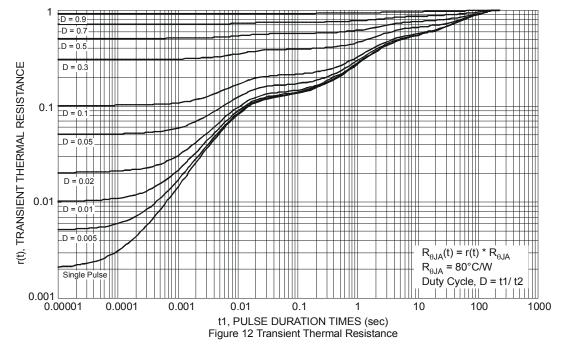






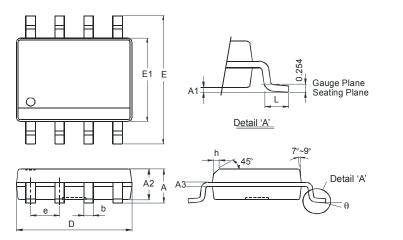






Package Outline Dimensions

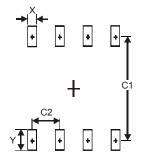
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
A3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Ш	5.90	6.10		
E1	3.85	3.95		
e	1.27 Typ			
h	- 0.35			
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Х	0.60
Y	1.55
C1	5.4
C2	1.27



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